

■ PRODUCT CHARACTERISTICS

VDSS	30V
$R_{DS(on)typ}(V_{GS}=10V)$	2.5mΩ
$R_{DS(on)Typ}(V_{GS}=4.5V)$	3.5mΩ
ID	150A

■ FEATURES

- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high EAS
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

■ APPLICATION

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

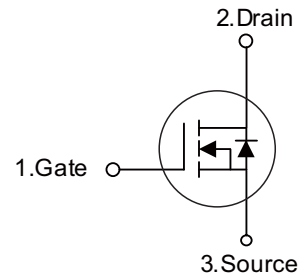
■ ORDER INFORMATION

Order codes		Package	Packing
Halogen-Free	Halogen		
N/A	MOT150N03A	TO-220	50 pieces/Tube

■ ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub> = 25°C, unless otherwise specified)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V <sub>DS</sub>	30	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Drain Current-Continuous	I <sub>D</sub>	150	A
Drain Current-Continuous(T <sub>C</sub> =100°C)	I <sub>D</sub> (100°C)	105	A
Pulsed Drain Current	I <sub>DM</sub>	600	A
Maximum Power Dissipation	P <sub>D</sub>	130	W
Derating factor		0.87	W/°C
Single pulse avalanche energy	E <sub>AS</sub>	1700	mJ
Repetitive avalanche energy	E <sub>AR</sub>	400	mJ
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 To 175	°C
Thermal Resistance,Junction-to-Case	R <sub>θJC</sub>	1.15	°C/W

Symbol



■ ELECTRICAL CHARACTERISTICS (T<sub>C</sub>=25°C, unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	30	35	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
<b>On Characteristics</b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.2	1.7	2.5	V
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	-	2.5	3.5	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A	-	3.5	4.8	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =10V, I <sub>D</sub> =20A	12	-	-	S
<b>Dynamic Characteristics</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, F=1.0MHz	-	6297	-	PF
Output Capacitance	C <sub>oss</sub>		-	866	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	672	-	PF
<b>Switching Characteristics</b>						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =15V, I <sub>D</sub> =20A, V <sub>GS</sub> =10V, R <sub>G</sub> =2.5Ω	-	26	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	24	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	91	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	39	-	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =15V, I <sub>D</sub> =20A, V <sub>GS</sub> =10V	-	114	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	22	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	19	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =20A	-	-	1.2	V
Diode Forward Current	I <sub>S</sub>		-	-	150	A
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25°C, I <sub>F</sub> = 20A	-	42	-	nS
Reverse Recovery Charge	Q <sub>rr</sub>	di/dt = 100A/μs	-	39	-	nC

■ TYPICAL CHARACTERISTICS

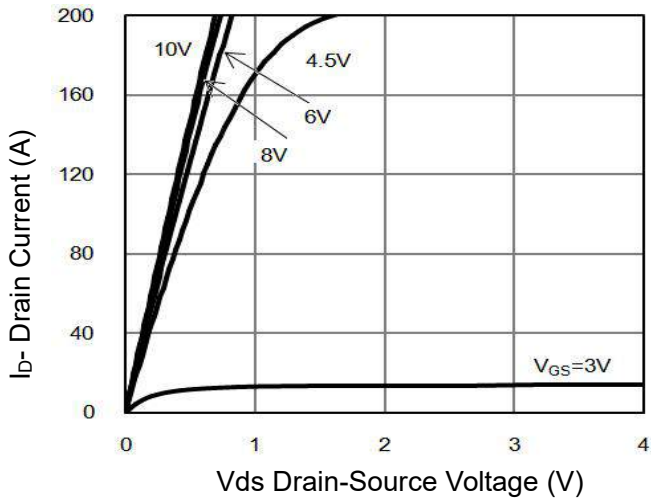


Figure 1 output characteristics

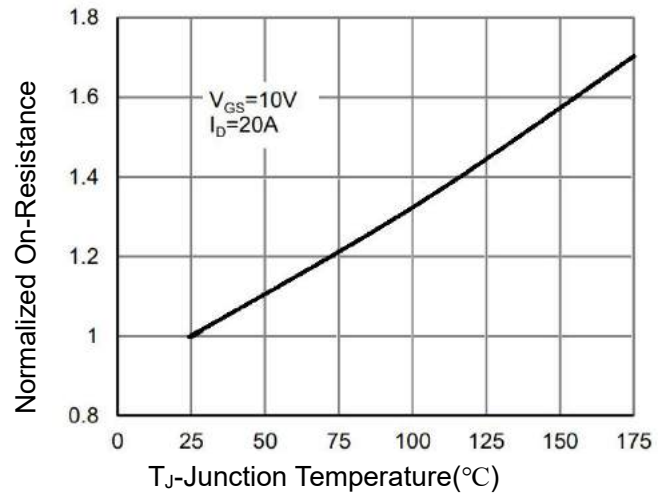


Figure 2 rdson-junction temperature

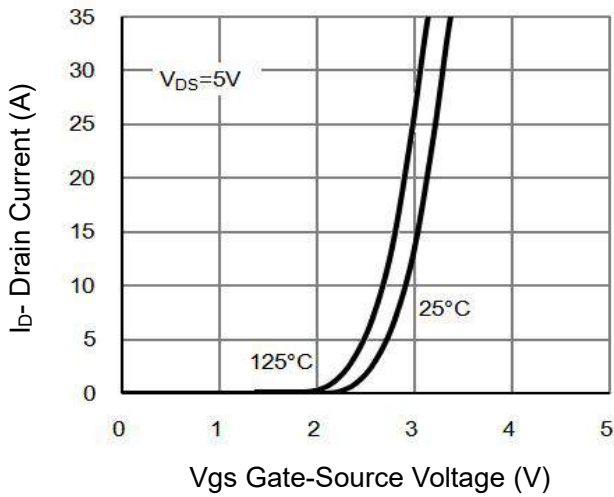


Figure 4 transfer characteristics

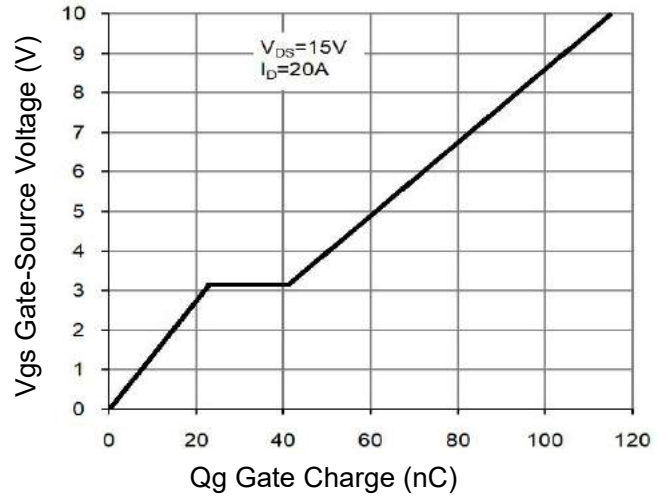


Figure 4 gate charge

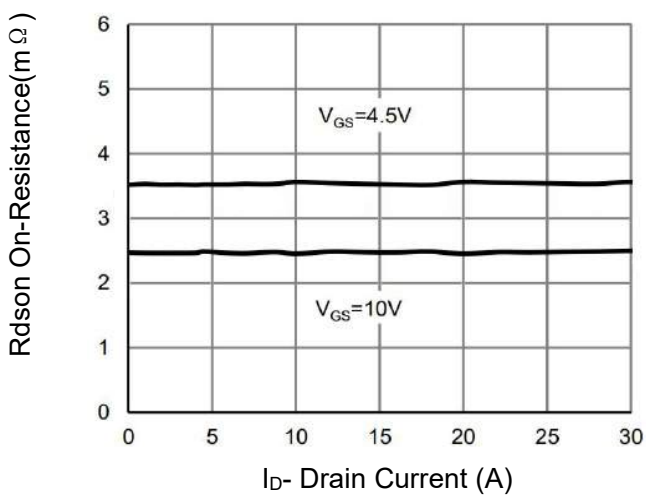


Figure 5 rdson-drain current

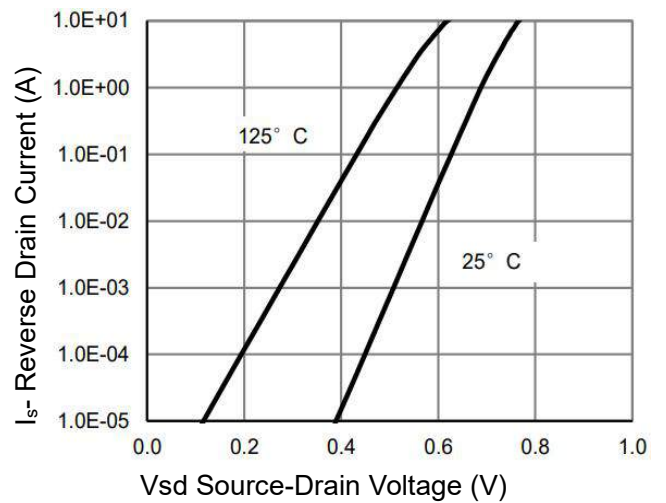


Figure 6 source-drain diode forward

■ TYPICAL CHARACTERISTICS(Cont.)

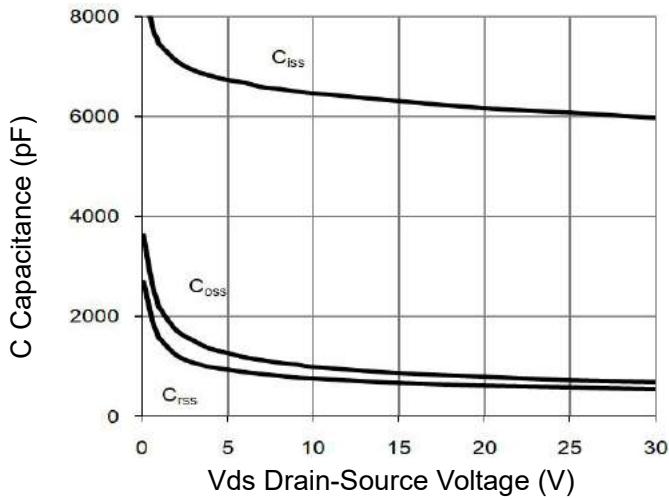


Figure 7 capacitance vs vds

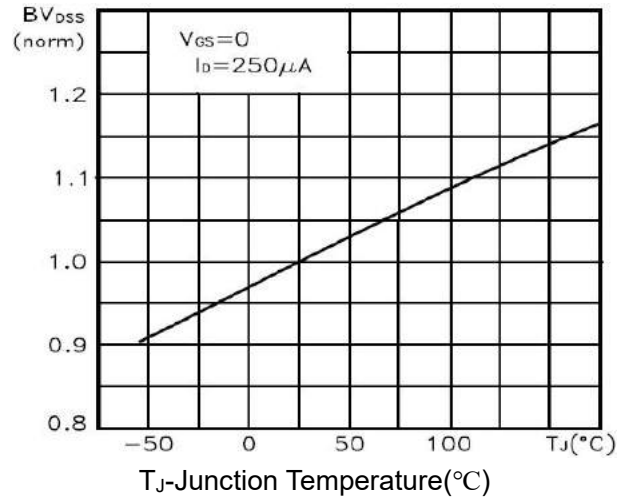


Figure 8 bvdss vs junction temperature

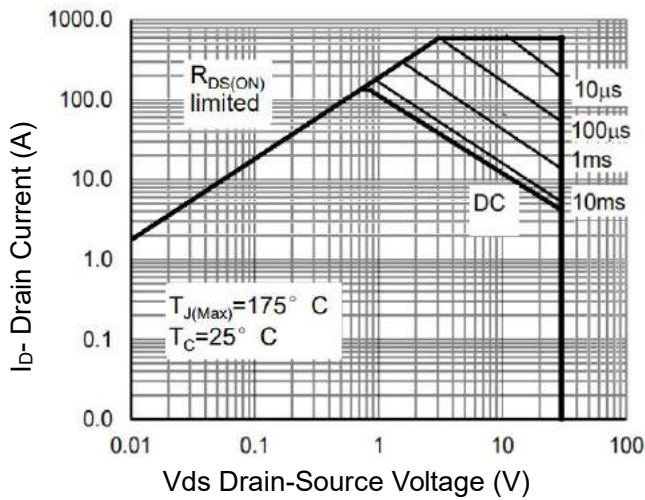


Figure 9 safe operation area

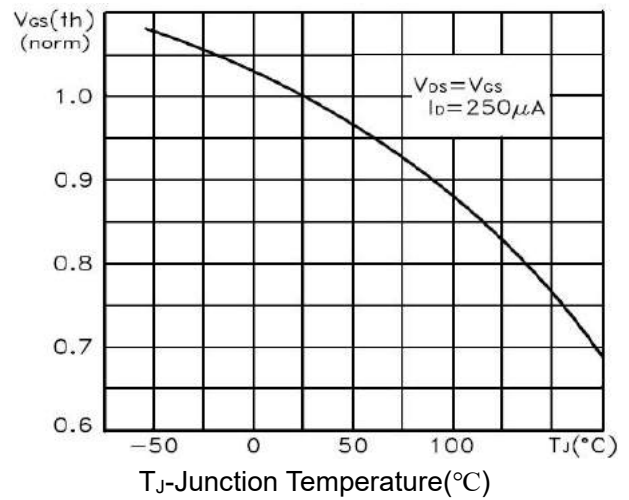


Figure 10 vgs vs junction temperature

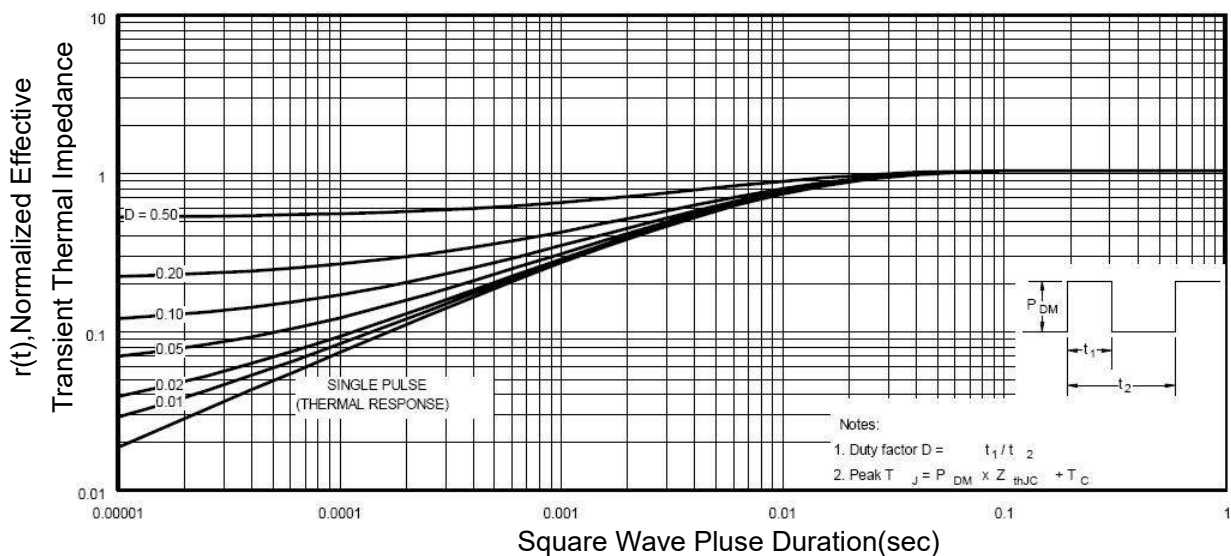


Figure 11 normalized maximum transient thermal impedance

■ TO-220-3L PACKAGE OUTLINE DIMENSIONS

